

cont
02

at right angles from each other. A size of the die pad 2 is smaller than the size of a semiconductor chip 11. That is, a configuration of the die pad 2 is smaller than that of the semiconductor chip."

Replace the paragraph beginning on page 4, line 26 with the following paragraph:

03

"After the semiconductor chip 11 is fixed on the die pad 2, electrode pads 15 arranged on a surface of the semiconductor chip 11 are connected to the inner leads through wires 13. During a wire-bonding step, the leadframe 1 is clamped on the heat stage 70 by a clasper 71, as shown in Fig. 8. A rear surface of the semiconductor chip 11 is vacuumed by a vacuuming portion 73 for holding the semiconductor chip 11 on the heat stage, as also shown in Fig. 8."

Replace the paragraph beginning on page 6, line 7 with the following paragraph:

04

"Also, a configuration of the stress-absorbing portions 7 can be S-shaped stress-absorbing portions 30, as shown in Fig. 3. In this case, as a protruding portion 31 is symmetrical with a concave portion 32, a changing in lateral or vertical directions of the die pad supporters 3 causing the expansion of die pad supporter 3 can be reduced."

In the Claims:

The following replacement claims are respectfully submitted: